

### IN THE CLAIMS

Please cancel claim 33. All pending claims and status indicators are listed below. This listing of claims will replace all prior versions and listings of claims in the application.

- 1-20. (Canceled)
30. (Previously Presented) A device comprising:  
a flexible substrate;  
a resistive region formed on the flexible substrate and having a first end and a second end, wherein the resistive region is formed in an activated region of the flexible substrate via a reaction between the activated region and a metal disposed on the activated region; and  
conductive terminals coupled to each of the first end and the second end.
31. (Original) The device, as set forth in claim 30, wherein the flexible substrate comprises a polyimide material.
32. (Original) The device, as set forth in claim 30, wherein the resistive region has a resistance in the range of 300 kohms - 1 Mohm.
33. (Cancelled)
34. (Original) The device, as set forth in claim 30, wherein the resistive region comprises a titanium-carbide.
35. (Original) The device, as set forth in claim 30, wherein the resistive region is formed at a temperature of less than 200°C.
36. (Previously Presented) The device, as set forth in claim 30, wherein the resistive region does not comprise a serpentine structure.
37. (Canceled)

38. (Original) The device, as set forth in claim 30, wherein each of the conductive terminals comprises a first layer of titanium.

39. (Original) The device, as set forth in claim 38, wherein each of the conductive terminals comprises a layer of copper.

40. (Original) The device, as set forth in claim 39, wherein each of the conductive terminals comprise a second layer of titanium disposed on the layer of copper.

41. (Original) The device, as set forth in claim 30, comprising a light emitting diode (LED) electrically coupled to each of the conductive terminals.

42. (Original) A device comprising:  
a flexible substrate having a first side and a second side;  
a light emitting diode (LED) coupled to the first side of the flexible substrate  
and electrically coupled to contact regions on the second side of the  
flexible substrate; and  
a resistor formed on the second side of the flexible substrate, wherein the  
resistor is electrically coupled between each of the contact regions.

43. (Original) The device, as set forth in claim 42, wherein the flexible substrate comprises a polyimide material.

44. (Original) The device, as set forth in claim 42, wherein the resistor has a resistance in the range of 300 kohms - 1 Mohm.

45. (Original) The device, as set forth in claim 42, wherein the resistor comprises a titanium-carbide region.

46. (Original) The device, as set forth in claim 42, wherein the resistor is formed at a temperature of less than 200°C.

47. (Original) The device, as set forth in claim 42, wherein the resistor does not comprise a serpentine structure.

48. (Original) The device, as set forth in claim 42, wherein the resistor is formed in an activated region on the second side of the flexible substrate via a reaction between the activated region and a metal disposed on the activated region.

49. (Original) The device, as set forth in claim 48, wherein the resistor comprises a metal-carbide region coupled between each of a first interconnect region and a second interconnect region.

50. (Original) The device, as set forth in claim 49, wherein each of the first and second interconnect regions comprises a first layer of titanium.

51. (Original) The device, as set forth in claim 50, wherein each of the first and second interconnect regions comprises a layer of copper.

52. (Original) The device, as set forth in claim 51, wherein each of the first and second interconnect regions comprise a second layer of titanium deposited on the layer of copper.